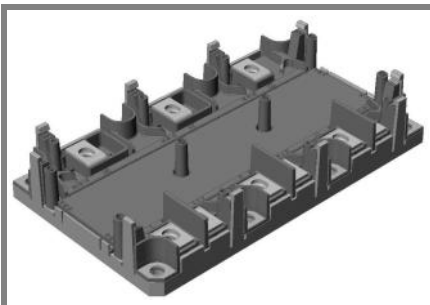


# SKiM455GD12T4D1



SKiM<sup>®</sup> 5

## Trench IGBT modules

SKiM455GD12T4D1

Preliminary Data

### Features

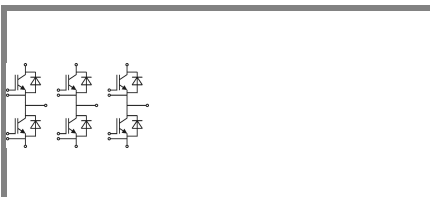
- IGBT 4 = Trenchgate technology
- $V_{CE(sat)}$  with positive temperature coefficient
- High short circuit capability

### Typical Applications\*

- High Reliability AC inverter drives
- UPS

### Remarks

- Case temperature limited to  $T_c = 125^\circ\text{C}$  max
- $T_{j,max}$  of the diode is limited to  $150^\circ\text{C}$

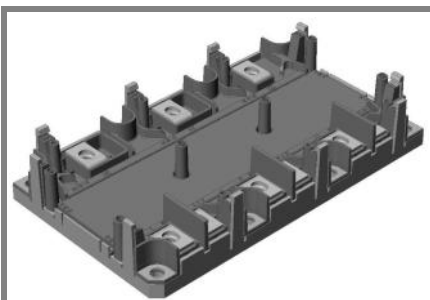


GD

Absolute Maximum Ratings		$T_c = 25^\circ\text{C}$ , unless otherwise specified		
Symbol	Conditions	Values	Units	
<b>IGBT</b>				
$V_{CES}$	$T_j = ^\circ\text{C}$	1200	V	
$I_C$	$T_j = 150^\circ\text{C}$	$T_{heatsink} = 25^\circ\text{C}$	400	A
		$T_{heatsink} = 70^\circ\text{C}$	305	A
$I_{CRM}$	$I_{CRM} = 3 \times I_{CNOM}$	1350	A	
$V_{GES}$		$\pm 20$	V	
$t_{psc}$	$V_{CC} = 800\text{ V}; V_{GE} \leq 15\text{ V}; T_j = 150^\circ\text{C}$ $V_{CES} < 1200\text{ V}$	10	$\mu\text{s}$	
<b>Inverse Diode</b>				
$I_F$	$T_j = 150^\circ\text{C}$	$T_{heatsink} = 25^\circ\text{C}$	295	A
		$T_{heatsink} = 70^\circ\text{C}$	215	A
$I_{FRM}$	$I_{FRM} = 2 \times I_{FNOM}$	600	A	
<b>Module</b>				
$I_{t(RMS)}$			A	
$T_{vj}$		-40 ... +150	$^\circ\text{C}$	
$T_{stg}$		-40 ... +125	$^\circ\text{C}$	
$V_{isol}$	AC, 1 min.	2500	V	

Characteristics		$T_c = 25^\circ\text{C}$ , unless otherwise specified					
Symbol	Conditions	min.	typ.	max.	Units		
<b>IGBT</b>							
$V_{GE(th)}$	$V_{GE} = V_{CE}, I_C = 18\text{ mA}$	5	5,8	6,5	V		
$I_{CES}$	$V_{GE} = 0\text{ V}, V_{CE} = V_{CES}$			5,0	mA		
$V_{CE0}$				$T_j = 25^\circ\text{C}$	0,8	0,9	V
				$T_j = 125^\circ\text{C}$	0,7	0,8	V
$r_{CE}$	$V_{GE} = 15\text{ V}$			$T_j = 25^\circ\text{C}$	2,2	2,4	$\text{m}\Omega$
				$T_j = 125^\circ\text{C}$	3,1	3,3	$\text{m}\Omega$
$V_{CE(sat)}$	$I_{Cnom} = 450\text{ A}, V_{GE} = 15\text{ V}$			$T_j = 25^\circ\text{C}_{chiplev.}$	1,8	2	V
				$T_j = 125^\circ\text{C}_{chiplev.}$	2,1	2,3	V
$C_{ies}$	$V_{CE} = 25, V_{GE} = 0\text{ V}$	$f = 1\text{ MHz}$			27,9		nF
$C_{oes}$					1,7		nF
$C_{res}$					1,5		nF
$Q_G$	$V_{GE} = -8\text{V}/+15\text{V}$				2600		nC
$R_{Gint}$	$T_j = 25^\circ\text{C}$				1,7		$\Omega$
$t_{d(on)}$	$R_{Gon} = 1\ \Omega$ $di/dt = 8200\text{ A}/\mu\text{s}$	$V_{CC} = 600\text{V}$ $I_C = 450\text{A}$			265		ns
$t_r$					60		ns
$E_{on}$					34		mJ
$t_{d(off)}$	$R_{Goff} = 1\ \Omega$ $di/dt = 5300\text{ A}/\mu\text{s}$	$V_{GE} = \pm 15\text{V}$			470		ns
$t_f$					65		ns
$E_{off}$					40		mJ
$R_{th(j-s)}$	per IGBT				0,14		K/W

# SKiM455GD12T4D1



**SKiM<sup>®</sup> 5**

## Trench IGBT modules

**SKiM455GD12T4D1**

Preliminary Data

### Features

- IGBT 4 = Trenchgate technology
- $V_{CE(sat)}$  with positive temperature coefficient
- High short circuit capability

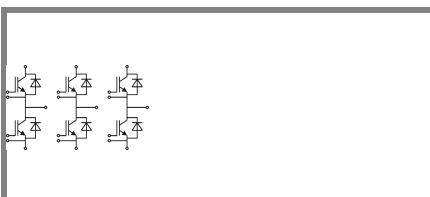
### Typical Applications\*

- High Reliability AC inverter drives
- UPS

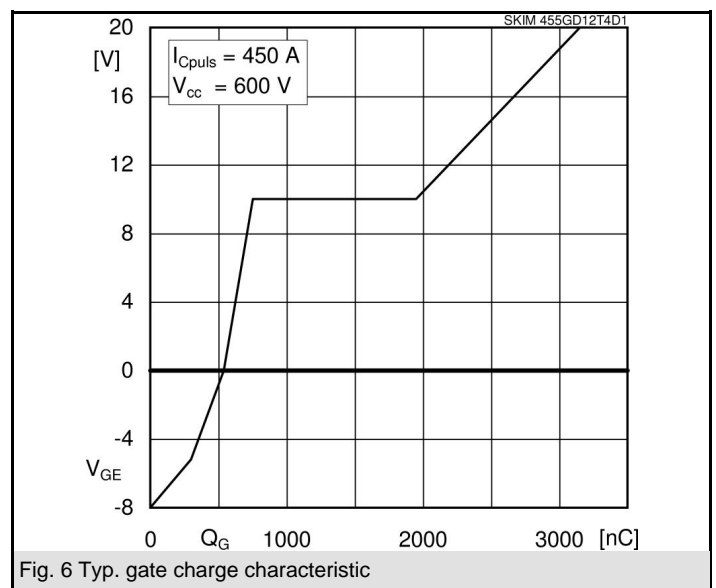
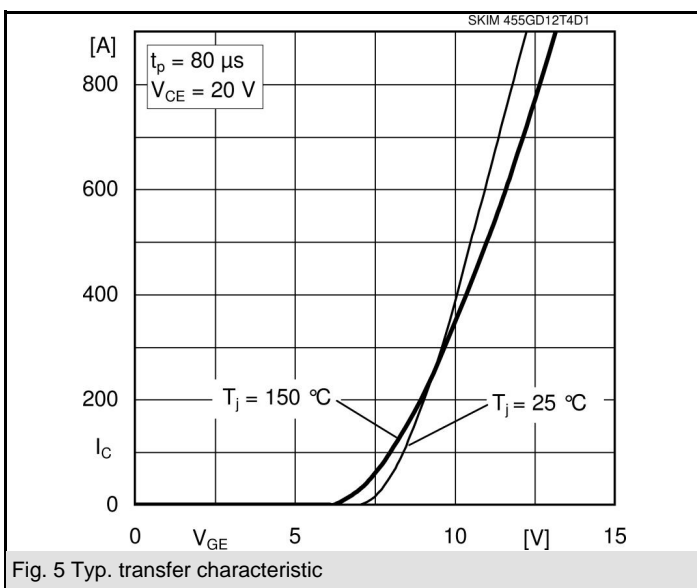
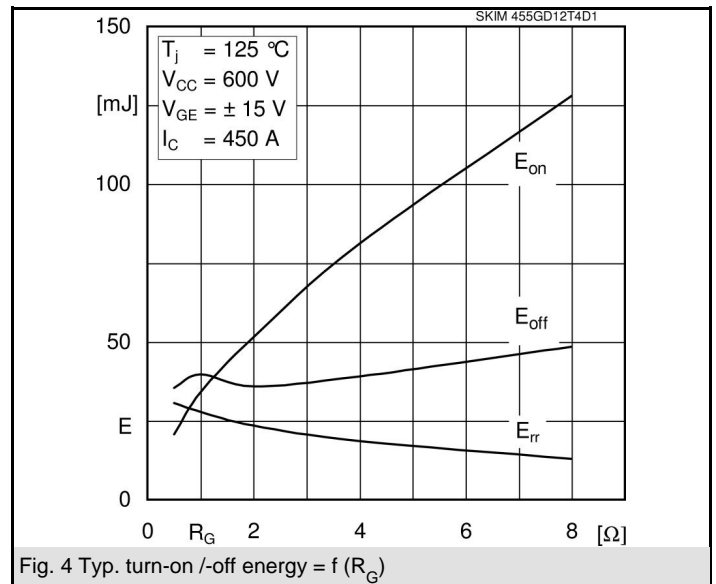
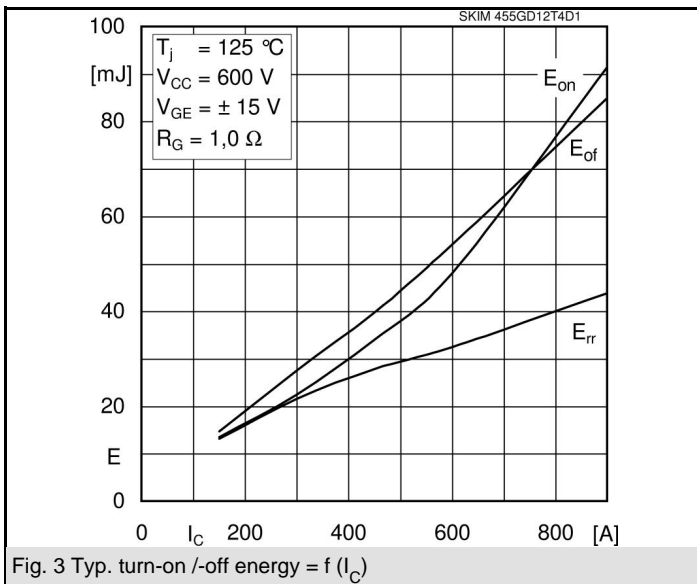
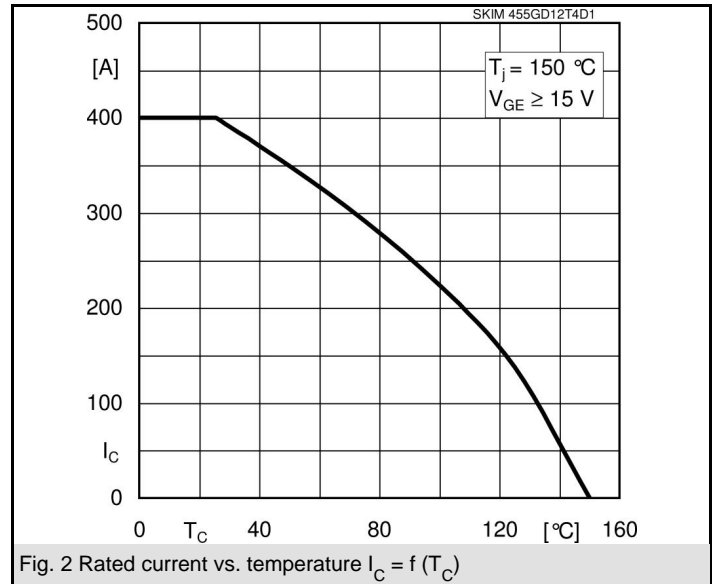
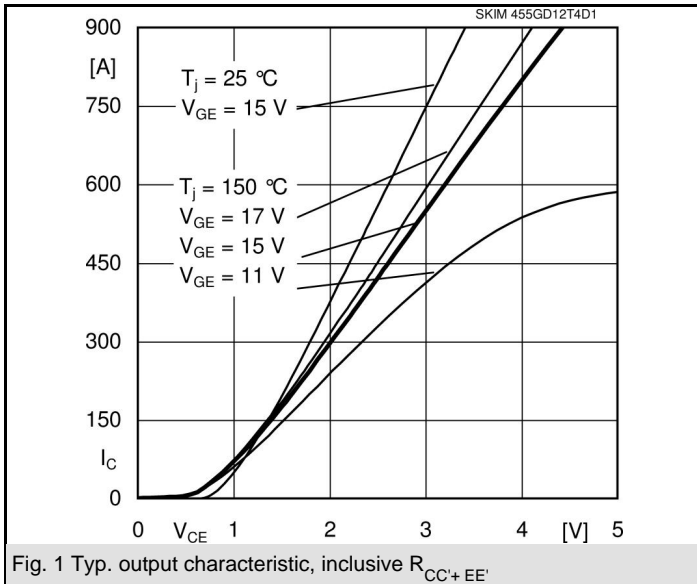
### Remarks

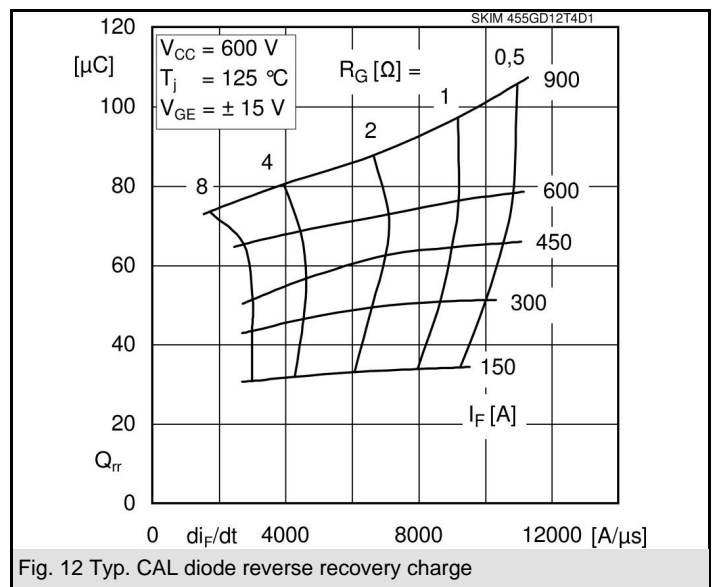
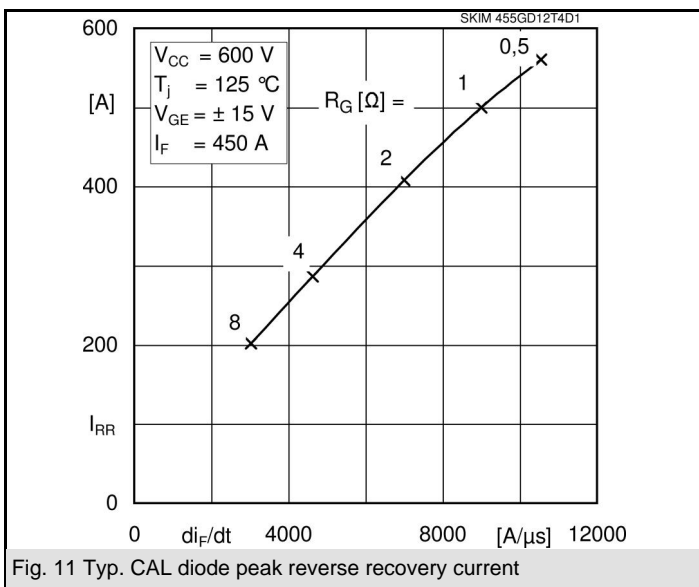
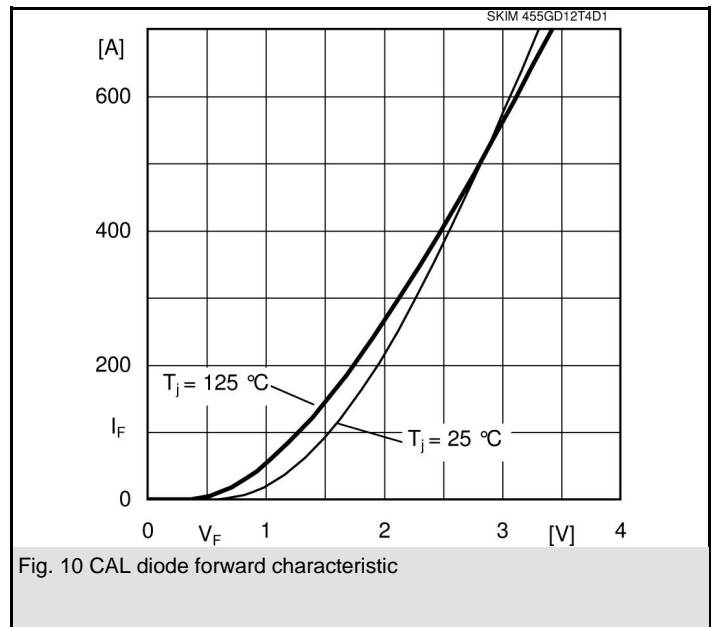
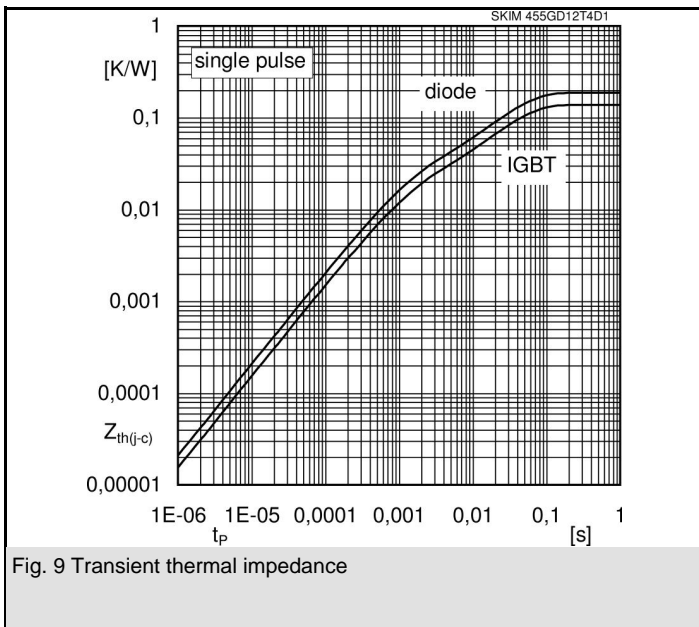
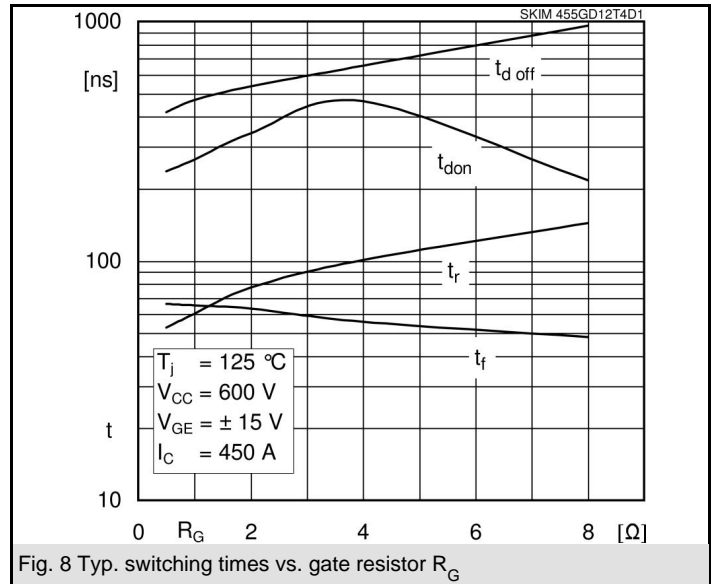
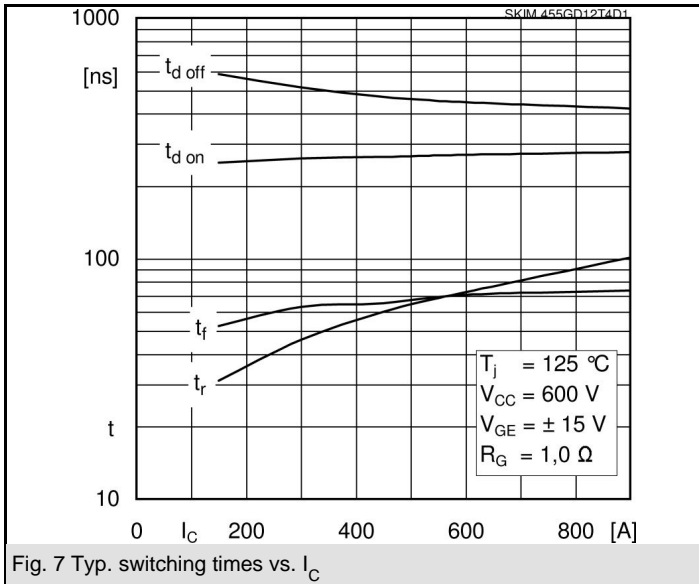
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- $T_{j,max}$  of the diode is limited to  $150^\circ\text{C}$

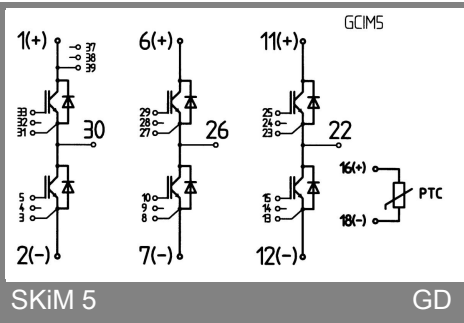
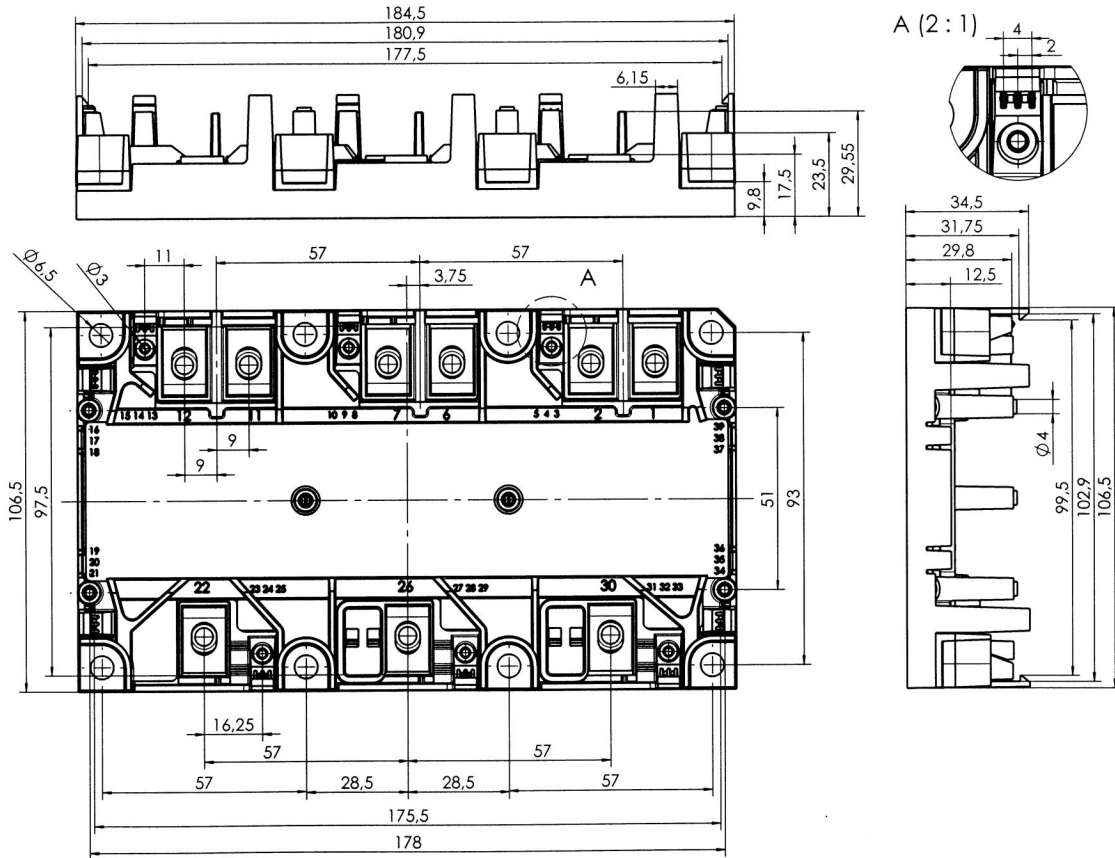
Characteristics		min.	typ.	max.	Units
<b>Symbol</b>	<b>Conditions</b>				
<b>Inverse Diode</b>					
$V_F = V_{EC}$	$I_{Fnom} = 450\text{ A}; V_{GE} = 0\text{ V}$		2,3	2,8	V
			2,2	2,7	V
					V
$V_{F0}$			1,2	1,6	V
			0,9	1,3	V
$r_F$			2,3	2,7	mΩ
			2,8	3,1	mΩ
$I_{RRM}$	$I_F = 450\text{ A}$		500		A
$Q_{rr}$	$di/dt = 9000\text{ A}/\mu\text{s}$		64,5		μC
$E_{rr}$	$V_{GE} = -15\text{ V}$		27,8		mJ
$R_{th(j-s)}$	per diode		0,19		K/W
<b>Module</b>					
$L_{CE}$				20	nH
$R_{CC'+EE'}$	res., terminal-chip	$T_{case} = 25^\circ\text{C}$	0,9		mΩ
		$T_{case} = 125^\circ\text{C}$	1,1		mΩ
$M_s$	to heat sink M5				Nm
$M_t$	to terminals M6		4	5	Nm
w				460	g
<b>Temperature sensor</b>					
$R_{TS}$	$T = 25 (100)^\circ\text{C}$		1 (1,67)		kΩ
Tolerance	$T = 25 (100)^\circ\text{C}$		3 (2)		%



**GD**







This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, chapter IX.

### \*IMPORTANT INFORMATION AND WARNINGS

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